



Simulations with TCAD

Tutorial



Overview

- 1.) Building a structure
 - Using a scheme command file
 - 2.) Define simulation parameters
 - Using an Input command file
- **Example: 'Simple' Diode**



1.) Geometry file

- A scheme file consists of
 - Parameter definitions
 - Geometry definitions
 - Doping profile definitions
 - Meshing definitions
 - Contact definitions and placements
 - Operation orders



1.A Parameter definition

- You could define:

- Geometry sizes:

- **(define Diode_thickness 320.0);**

(define Diode_width 500.0); (define Oxide_thickness 1.2); (define Al_thickness 1); (define Doping_thickness_BP 10); (define Doping_thickness_implant 1); (define Connection_hole_width 10)

- Or doping concentrations

- **(define concentration_bulk 1.5e12);**

(define concentration_implant 1e19); (define concentration_BP 1e19)



1.B Geometry

- (sdegeo:create-rectangle (position 0 0 0)
(position Diode_width Diode_thickness 0)
"Silicon" "bulk")

Material could be a default material or a self define material; material properties could be change in the Material.par file

- (sdegeo:create-rectangle (position 0 (* -1 Oxide_thickness) 0) (position Diode_width (* -1
(+ Oxide_thickness Al_thickness)) 0) "Aluminum" "TopCon")

Epsilon

{ * Ratio of the permittivities of material and vacuum

* epsilon() = epsilon

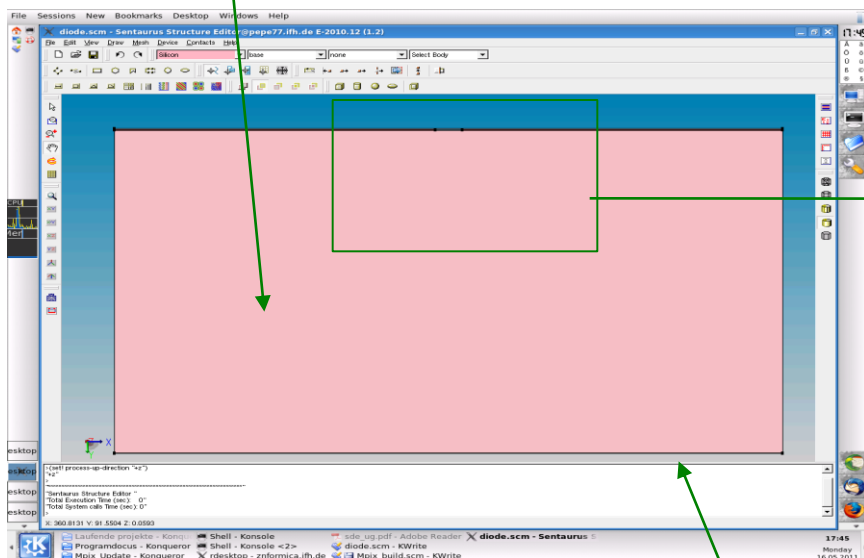
epsilon = 11.9 # default 11.7[1] }



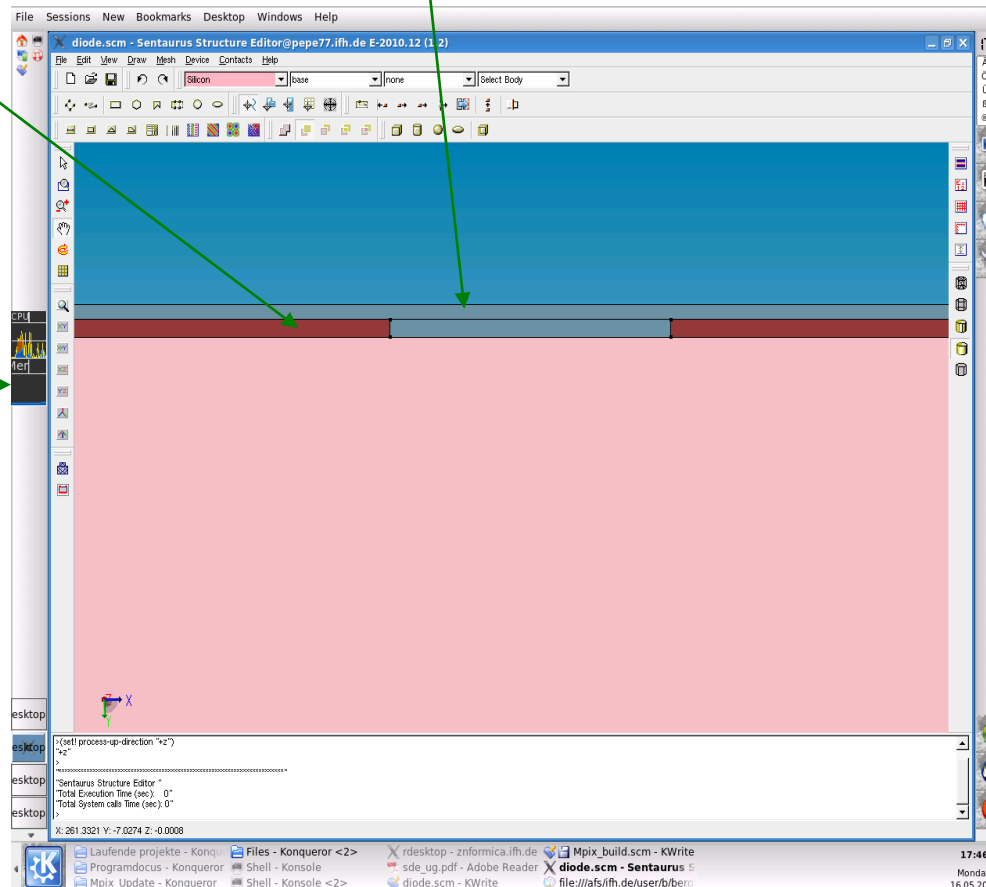
Top metal

SiO_2

Bulk-Si



BP metal



1.C Doping profile

I – Reference Window



- (sdedr:define-refeval-window "BP_DopingRefWin" "Line" (position 0 Diode_thickness 0) (position Diode_width Diode_thickness 0))
- (sdedr:define-refeval-window "Top_DopingRefWin" "Line" (position 0 0 0) (position Diode_width 0 0))



1.C Doping profile

II – Profile definition

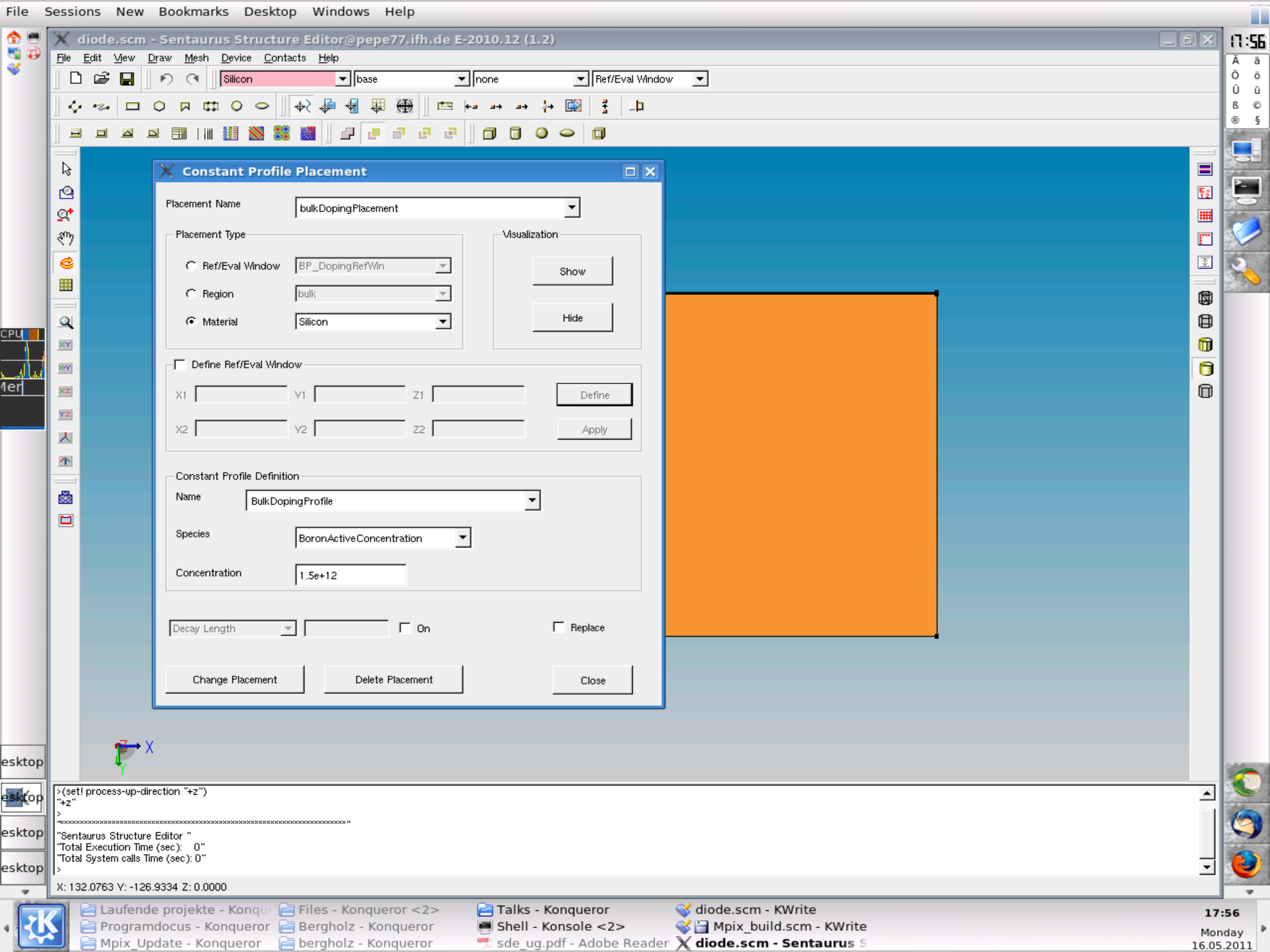
- (sdedr:define-constant-profile "BulkDopingProfile" "BoronActiveConcentration" concentration_bulk)
- (sdedr:define-gaussian-profile "BPDopingProfile" "BoronActiveConcentration" "PeakPos" 0 "PeakVal" concentration_BP "ValueAtDepth" concentration_bulk "Depth" Doping_thickness_BP "Gauss" "Factor" 0.5)
- (sdedr:define-gaussian-profile "TopDopingProfile" "PhosphorusActiveConcentration" "PeakPos" 0 "PeakVal" concentration_implant "ValueAtDepth" concentration_bulk "Depth" Doping_thickness_implant "Gauss" "Factor" 0.5)



1.C Doping profile

III – Create the profile

- (sdedr:define-constant-profile-material
"bulkDopingPlacement" "BulkDopingProfile" "Silicon")
- (sdedr:define-analytical-profile-placement
"BPDopingPlacement" "BPDopingProfile"
"BP_DopingRefWin" "Both" "NoReplace" "Eval")
- (sdedr:define-analytical-profile-placement "TopDopingPlacement" "TopDopingProfile"
"Top_DopingRefWin" "Both" "NoReplace" "Eval")





1.D Meshing

I – Reference window

- (sdedr:define-refeval-window "surfaceRefinementPlacement" "Rectangle" (position 0 0 0) (position Diode_width (* thickness_implant 1.5) 0))
- (sdedr:define-refeval-window "overshootRefinementPlacement" "Rectangle" (position 0 0 0) (position Diode_width (* (+ Al_thickness Oxide_thickness) -1) 0))
- (sdedr:define-refeval-window "bulkRefinementPlacement" "Rectangle" (position 0 (* thickness_implant 1.5) 0) (position Diode_width (- Diode_thickness (* thickness_BPimplant 1.5)) 0))
- (sdedr:define-refeval-window "BPRefinementPlacement" "Rectangle" (position 0 (- Diode_thickness (* thickness_BPimplant 1.5)) 0) (position Diode_width (+ Diode_thickness Al_thickness) 0))



1.D Meshing

II – Refinement

- (sdedr:define-refinement-size "surfaceRefinementSize" (/ Diode_width 200) (/ Doping_thickness_implant 20) (/ Diode_width 2000) (/ Doping_thickness_implant 200))
- (sdedr:define-refinement-size "overshootRefinementSize" (/ Diode_width 20) (/ Oxide_thickness 2) (/ Diode_width 200) (/ Oxide_thickness 10))
- (sdedr:define-refinement-size "BulkRefinementSize" (/ Diode_width 10) (/ Diode_thicknes 20) (/ Diode_width 200) (/ Diode_thicknesr 100))
- (sdedr:define-refinement-size "BPRefinementSize" (/ Diode_width 50) (/ Doping_thickness_BP 10) (/ Diode_width 250) (/ Doping_thickness_BP 100))

1.D Meshing

III – Refinement function



- (sdedr:define-refinement-function "surfaceRefinementSize" "DopingConcentration" "MaxGradient" 1)
- (sdedr:define-refinement-function "overshootRefinementSize" "DopingConcentration" "MaxGradient" 1)
- (sdedr:define-refinement-function "BulkRefinementSize" "DopingConcentration" "MaxGradient" 1)
- (sdedr:define-refinement-function "BPRRefinementSize" "DopingConcentration" "MaxGradient" 1)

1.D Meshing

IV – Build the Refinement

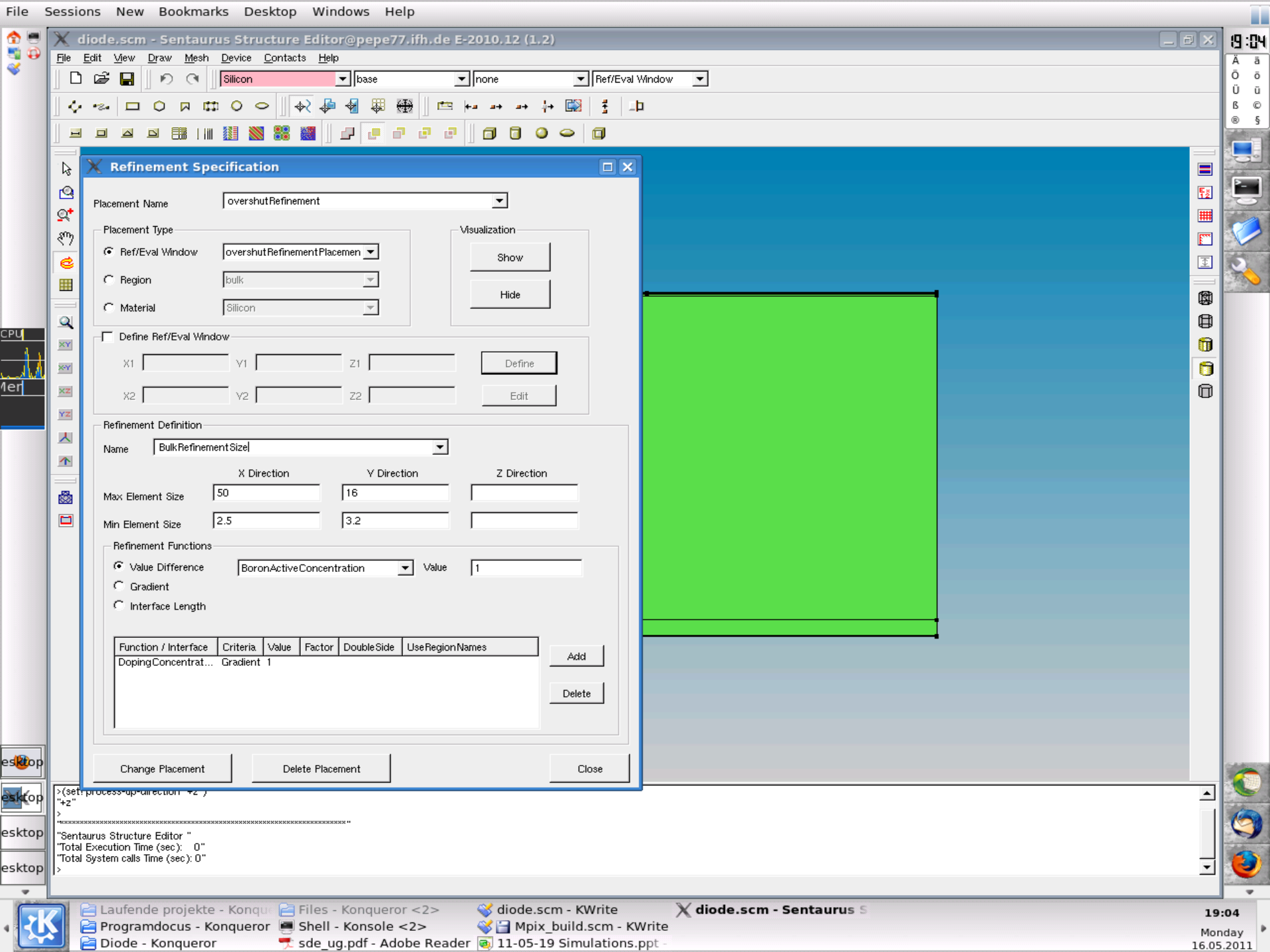


```
(sdedr:define-refinement-placement "surfaceRefinement"  
  "surfaceRefinementSize"  
  "surfaceRefinementPlacement")
```

```
(sdedr:define-refinement-placement "overshootRefinement" "overshootRefinementSize"  
  "overshootRefinementPlacement")
```

```
sdedr:define-refinement-placement "bulkRefinement" "BulkRefinementSize"  
  "bulkRefinementPlacement")
```

```
(sdedr:define-refinement-placement "BPRRefinement" "BPRRefinementSize"  
  "BPRRefinementPlacement")
```





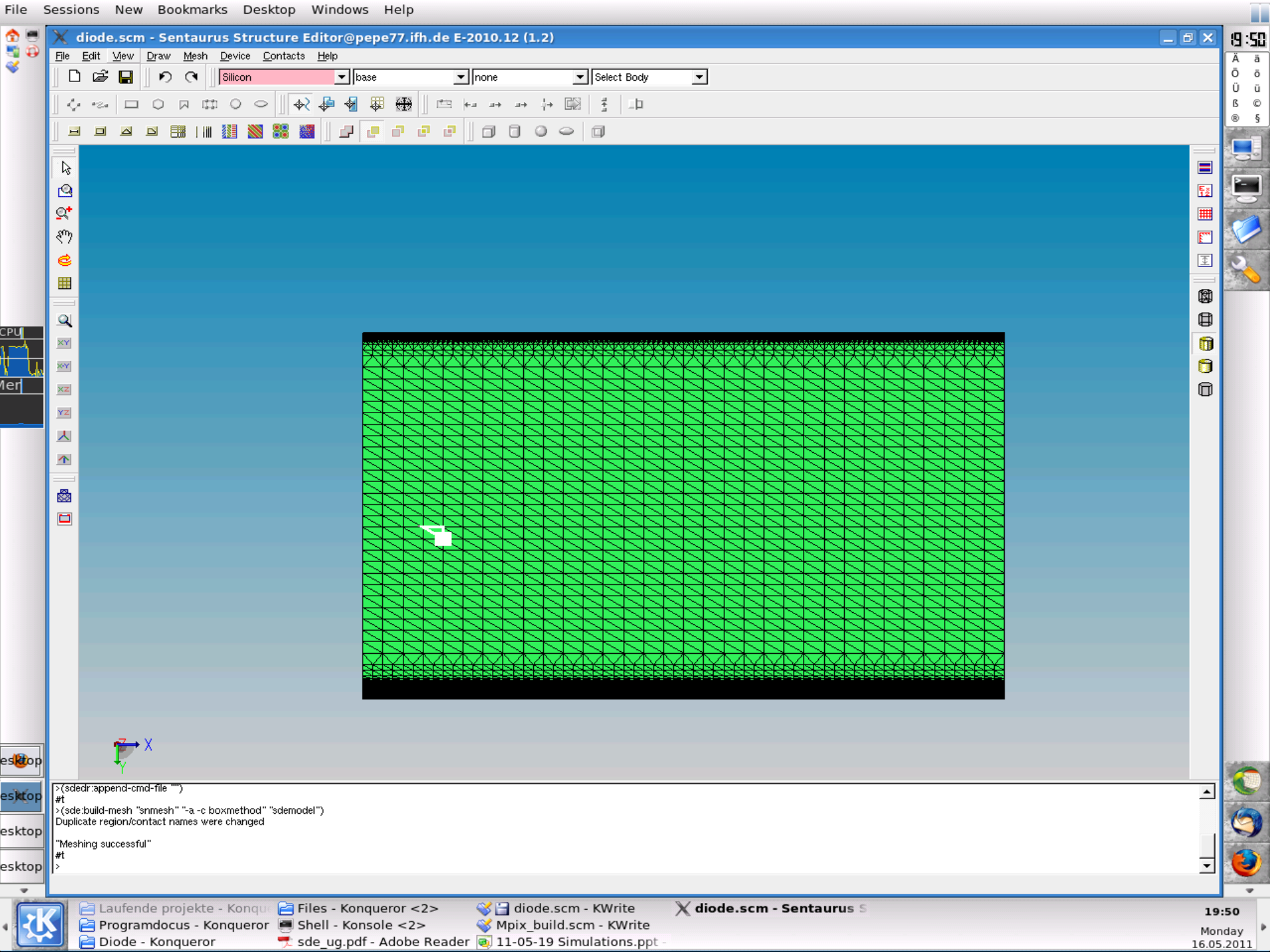
1.E Contact definition

- `(sdegeo:define-contact-set "BPContact" (color:rgb 1 0 0) "##")`
- `(sdegeo:define-2d-contact (list (car (find-edge-id (position (/ Diode_width 2) Diode_thickness 0))) (car (find-edge-id (position 0 (+ Diode_thickness (/ Al_thickness 2)) 0))) (car (find-edge-id (position Diode_width (+ Diode_thickness (/ Al_thickness 2)) 0))) (car (find-edge-id (position (/ Diode_width 2) (+ Diode_thickness Al_thickness) 0)))) "BPContact")`



Starting with mesh building

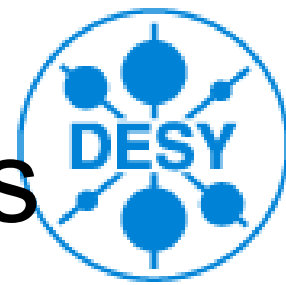
- Additional Options
 - `(sde:save-model`
 `"/afs/afh.de/group/cms/bergholz/daten/TCAD/Diode/`
 `diodeModel")`
 - `(sde:build-mesh "snmesh" "-a -c boxmethod"`
 `"/afs/afh.de/group/cms/bergholz/daten/TCAD/Diode/`
 `diodeMesh")`
- **`sde -e -l SchemeFile.scm`**





2. Simulation

- The input file for the device simulation consists of
 - An input and output file definition
 - An Electrode definition
 - A definition of the used physical models
 - Plot and math selections
 - Spice transformation for capacitance
 - Simulation order 'Voltage ramps'



2.A File input and contacts

- File { * input files
- **Grid** = "DiodeMesh_msh.tdr"
- **Doping** = "DiodeMesh_msh.tdr"
- **Parameter** = "Silicon.par" $\leftarrow \varepsilon, \tau$
- * output file
- **Current** = "Diode_des.plt"}
- **Electrode** {
- {**Name** = "BPContact" **voltage** = 0.0 **Material** = "Aluminum" }
- {**Name** = "TopContact" **voltage** = 0.0 **Material** = "Aluminum" }}
- Name must be the same than in model!
- "Barrier=-0.55"

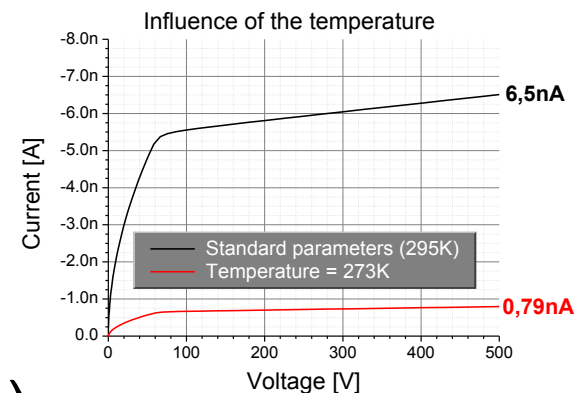
2. B “Standard” physical models

Physics {

Temperature = 295

Fermi #Using Fermi Statistic

EffectiveIntrinsicDensity
(BandGapNarrowing(Slotboom))



$$E_g(T) = E_g(0) - \frac{\alpha^2}{T + \beta}$$

$$E_g = E_g(0) \left[1 - \frac{N_{tot}}{N_{ref}} \right] + \sqrt{\left(1 - \frac{N_{tot}}{N_{ref}} \right)^2} \alpha$$

2.B Mobility models

- Mobility (

Doping Dependence

(High Field Saturation)

Carrier Carrier Scattering (Conwell-Weisskopf)

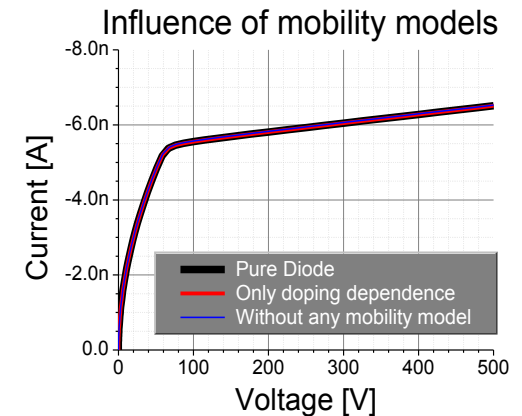
Enormal)

Masetti model

$$\mu_{eff} = \mu_{min} \left(\frac{E}{E_{sat}} \right)^{\alpha} \left(\frac{N_D}{N_A} \right)^{\beta}$$

Conwell-Weisskopf-Model

$$\mu_{eff} = \mu_{min} \left(\frac{E}{E_{sat}} \right)^{\alpha} \left[1 + \frac{1}{\sqrt{np}} \left(\frac{T}{T_0} \right)^{\beta} \right]$$



2.B Recombination models



- Recombination (

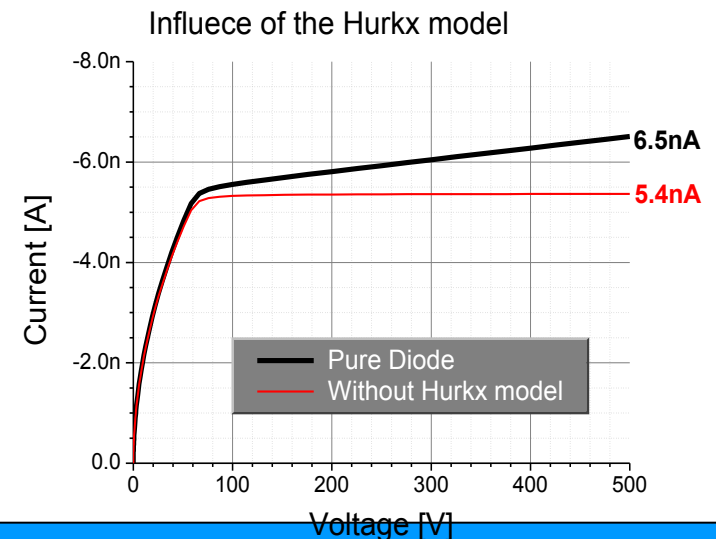
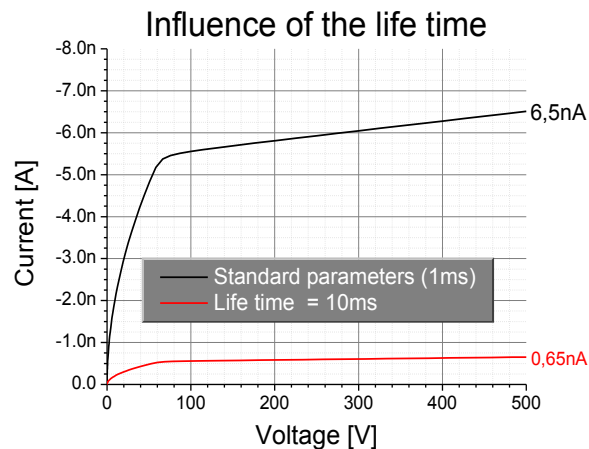
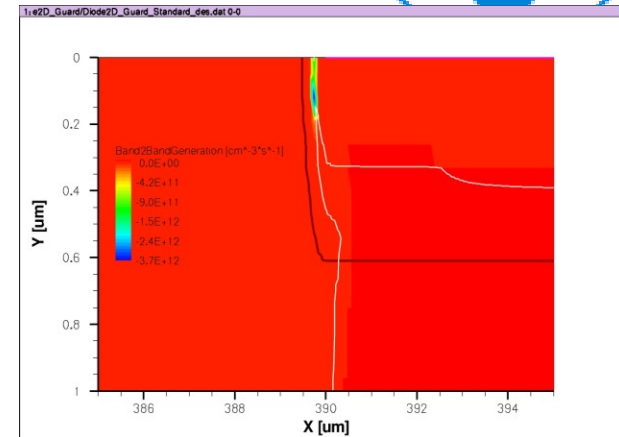
SRH (DopingDependence TempDependence

ElectricField (Lifetime=Hurkx))

Auger

eAvalanche (vanOverstraeten) hAvalanche (vanOverstraeten)

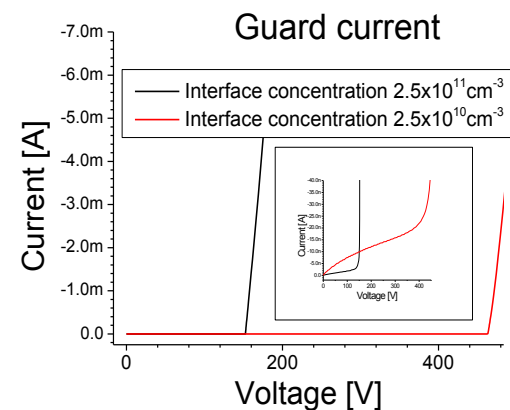
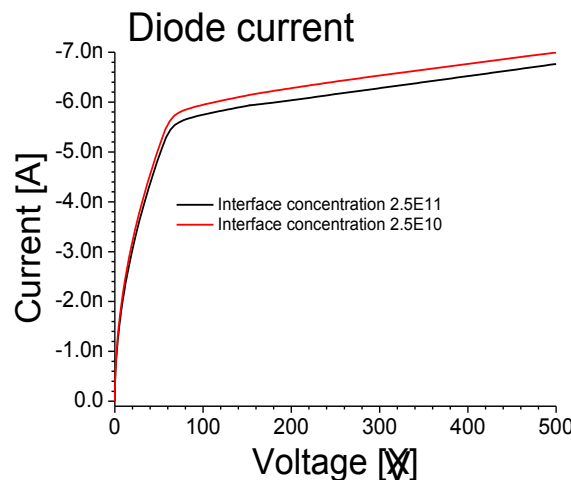
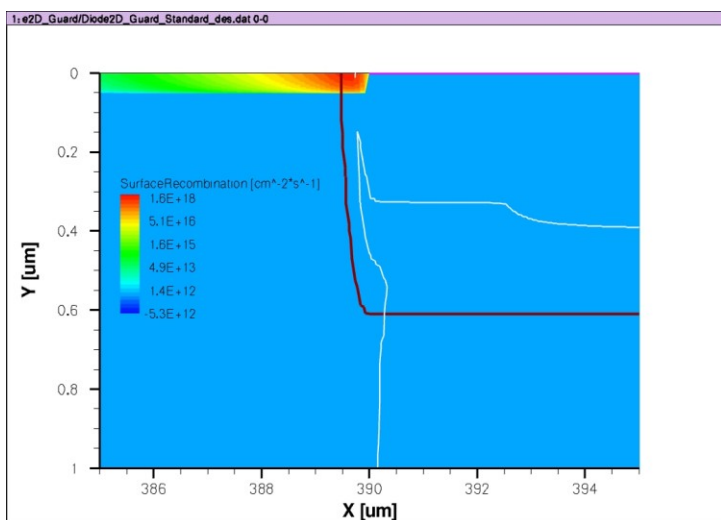
Band2Band(Hurkx))}





2.B Material Interface

- Physics (`MaterialInterface="Silicon/Oxide"`)
{`Charge(Conc=1.1e10)` `Recombination(surfaceSRH)`}





2.C Plot selection

- Plot{

eDensity hDensity eMobility hMobility

ElectricField/Vector Potential SpaceCharge

*--Generation/Recombination

SRH Band2Band Auger SurfaceRecombination

eLifetime hLifetime

* -Driving forces

eEparallel hEparallel eENormal hENormal

BandGap BandGapNarrowing}



2.D Math selection

- Math {
Method = pardiso
ACMethod = Blocked
Number_of_Threads = 4
Derivatives
RelErrControl
Iterations = 25}

2.E Spice transformation



- System {
Diode trans (BPContact=a TopContact=b)
Vsource_pset vBP (a 0) {dc=0}
Vsource_pset vTop (b 0) {dc=0}}



Solve

- Solve {
 #-a) Initial
 Poisson
 Coupled { Poisson Electron Hole }
 #-b) ramp IV
 QuasiStationary (
 InitialStep=1e-6 Minstep=1e-10 MaxStep=2e-3
 Increment=1.25 Decrement=4
 Goal { parameter =vBP.dc voltage = -1000 })



- #-c) ramp CV

{ACCoupled (

StartFrequency=1e6 EndFrequency=1e6

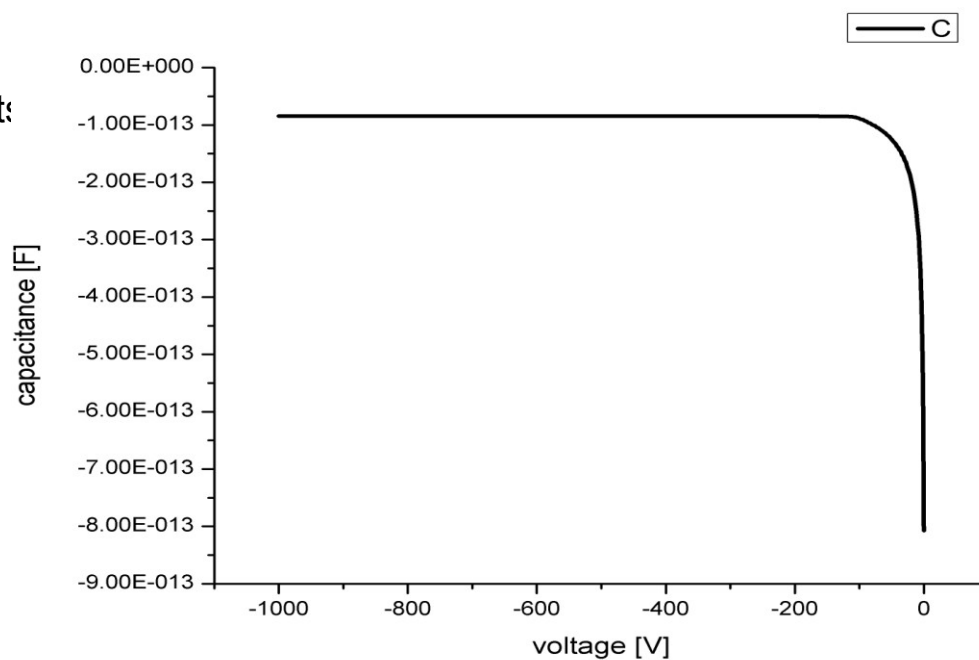
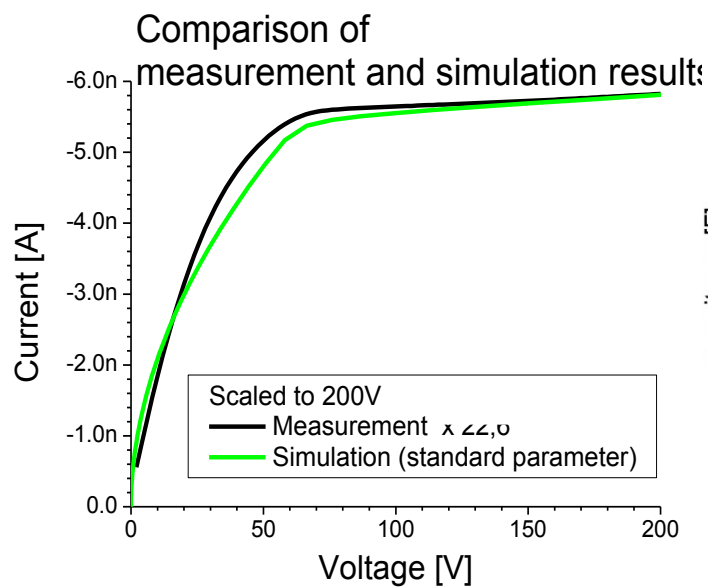
NumberOfPoints=1 Decade

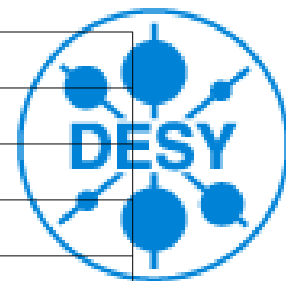
Node(a b) Exclude(vTop vBP))

{ Poisson Electron Hole }}}



Results





	Peak value	Additional Information
Silicon		
Epsilon	1.19E+01	
lifetime[ms]	4	
Poly-Silicon		
Thickness[um]	5	(Mpix)
Oxide		
Oxide charge	1.5	
Charge [cm-3]	1.00E+10	
Metal (Al)		
thickness [um]	1	
Contact barrier	-0.55?	
Doping		
bulk-Doping [cm-3]	1.50E+12	
Pad-Doping [cm-3]	1.00E+19	Gauss, Faktor 0.5
Top-doping thickness[um]	1.20E+00	
Backplan-doping[cm-3]	1.00E+19	
Backplane-thickness[um]	1.00E+02	
P-Stop [cm-3]	1.00E+16	???
p-Stop thickness	1	???
p-Stop Width	4	
p-Spray [cm-3]	How ???	
p-Spray thickness	to ???	
p-Spray width	implement ???	

17 May 2011

Used Parameters



Conclusions

- TCAD Software is a strong and power full tool for device simulation
- BUT the quality of the output strongly depends of the knowledge of the physical properties of the simulated device



Appendix



Parameter	Electrons	Holes
μ_1	43,4cm ² /Vs	29cm ² /Vs
$\mu_{\min 1}$	52,2cm ² /Vs	44,9cm ² /Vs
$\mu_{\min 2}$	52,2cm ² /Vs	0
P_c	0	9,23*10 ¹⁶ cm ⁻³
C_f	9,68*10 ¹⁶ cm ⁻³	2,23*10 ¹⁷ cm ⁻³
C_s	3,43*10 ²⁰ cm ⁻³	6,1*10 ²⁰ cm ⁻³
α	0,68	0,719
β	2	2